Terminal Pad Solderability:
Meets EIA Specification RS186-9E
And ANSI/J-STD-002 Category 3.

Terminal Pad Materials:
Tin-plated Nickel-Copper

Lead-Free, RoHS Compliant

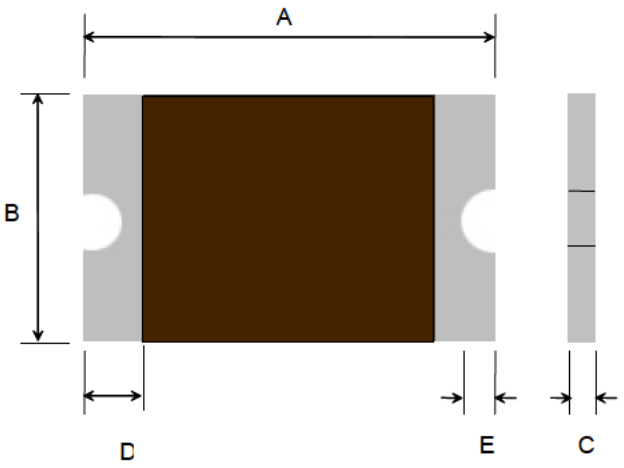

TABLE I. DIMENSIONS:

Model	Marking	A		B		C		D
		Min.	Max.	Min.	Max.	Min.	Max.	Min.
BpS03-250-09	2	1.45	1.85	0.65	1.05	0.40	1.00	0.15

Unit:mm

TABLE II. PERFORMANCE RATING:

Model	Marking	V_{max}	I_{max}	I_{hold}	I_{trip}	P_d	Maximum Time To Trip		Resistance	
				@25°C	@25°C	Typ.	Current	Time	Ri_{min}	$R1_{max}$
		(Vdc)	(A)	(A)	(A)	(W)	(A)	(Sec)	(Ω)	(Ω)
BpS03-250-09	2	9.0	40	0.25	0.55	0.50	8.0	0.08	0.500	3.000

Ihoid = Hold Current. Maximum current device will not trip in 25°C still air.
Itrip = Trip Current. Minimum current at which the device will always trip in 25°C still air.
Vmax = Maximum operating voltage device can withstand without damage at rated current (Imax).
Imax = Maximum fault current device can withstand without damage at rated voltage (Vmax).
Pd = Maximum power dissipation when device is in the tripped state in 25°C still air environment at rated voltage.
Rimin/max = Minimum/Maximum device resistance prior to tripping at 25°C.
R1max = Maximum device resistance is measured one hour post reflow.
CAUTION : Operation beyond the specified ratings may result in damage and possible arcing and flame.